



PCN# : P49DAA
Issue Date : May. 04, 2015

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Aug. 02, 2015

Expected First Date Code of Changed Product :1532

Description of Change (From) :

Front-end Wafer Fabrication site change from Fairchild Salt Lake Utah, 6-inch wafers

Back-end Assembly/Test site change from Fairchild Penang, Malaysia

Assembly Site	Fairchild Penang		Hana AYT
Package	Molded Leadless Package (MLP)/ Ultrathin MLP (uMLP)	Premolded Micropak/ MicroMLP (uMLP)	BT Micropak
Lead frame	ASM/ HaeSung DS/ Sumitomo PPF (pre-plated leadframe)		Kinsus Bismaleimide Triazine (BT) CCL-HL832 substrate
Die attach material	Henkel QMI519/ Hitachi EN-4620K/ Henkel 8008-HT/ Lintec LE5003	Lintec LE5003	Lintec LE5003
Wire	0.8, 1, 1.3, 1.5, 2 mil Au wire / 1.0, 1.5, 2 mil PdCu/ Cu	0.8 mils Au wire	0.8mils Au wire
Mold Compound	Hitachi CEL9220HF13FC1 (Green)	Cookson CK203P (Premold), CK203M (Final Mold) (Green)	Nitto GE-100-LFCG (Green)
Terminal Finish	NiPdAuAg/ NiPdAu		NiAu

Description of Change (To) :

Front-Wafer Fabrication site change to Mt. Top, Pennsylvania, 8-inch wafers and Tower Jazz Israel 8" Foundry

Back-end Assembly/Test site change to Hana, UTAC, and GEM subcontractors

Assembly Site	Hana AYT	UTAC	Hana AYT	UTAC
Package	Molded Leadless Package (MLP)/ Ultrathin MLP (UMLP)		Micropak/ MicroMLP (uMLP)	
Lead frame	HaeSung DS RT UPG1 PPF		ASM ME2 PPF/ Kinsus BT CCL-HL832 substrate	HaeSung DS RT UPG1 PPF/ Sumitomo selective PPF
Die attach	Henkel 8600/ CDF215	Henkel 8600/ CDF550	Henkel 8006NS (both) Lintec LE5003 (Hana)/ Henkel 8600 (UTAC)	
Wire	0.8, 1, 1.3, 1.5, 2 mil Au wire / 1.0, 1.5, 2 mil Cu/ PdCu (Hana), PdCuAg (UTAC)		Au 0.8mils	
Mold Compound	Hitachi CEL9220HF13H (Green)	Sumitomo G700LTD/ G770HCD (Green)	Hitachi CEL9220HF13H (Green)	Sumitomo G770HCD/ G700LTD/ Panasonic CV8715BT (Green)
Terminal Finish	NiPdAuAg		NiPdAu/ NiAu	NiPdAuAg/ NiPdAu

Item	Change From	Change To
Fabrication Site	Salt Lake	MountainTop/Tower Jazz
Assembly Site	FSPM	GEM
Lead frame	Bare Cu	Bare Cu
Die attach	84-1LMISR4	ABP8062T/ CT285
Wire bond	Cu/Au wire	Cu/Au wire
Molding	AMC-2P GR828FC1	G600FL

Not all parts in this PCN will undergo Assembly Changes. Please refer to table for device-specific changes.

Product ID	tech	Package	New FAB + New ASSEMBLY Sites
FDC637BNZ	PT4 N Z	SSOT6	FCS MTOP PA 8" + No Change
FDMA1032CZ	PT4 N Z, ST3 P Z	MLP	FCS MTOP PA 8" + UTAC
FDMA2002NZ	PT4 N Z	MLP	FCS MTOP PA 8" + UTAC
FDMA410NZ	PT4 N Z	MLP	FCS MTOP PA 8" + UTAC
FDMA420NZ	PT4 N Z	MLP	FCS MTOP PA 8" + No Change
FDMA430NZ	PT4 N Z	MLP	FCS MTOP PA 8" + UTAC
FDME1024NZT	PT4 N Z	MLP	FCS MTOP PA 8" + HANA/UTAC
FDME1034CZT	PT4 N Z, ST3 P Z	MLP	FCS MTOP PA 8" + HANA
FDS8858CZ	PT4 N Z, ST3 P Z	SO8	FCS MTOP PA 8" + GEM
FDG1024NZ	PT4 N Z	SC70_6WB_CB	FCS MTOP PA 8" + No Change
FDMC6890NZ	PT2 N, PT4 N Z	MLP	Tower Israel, FCS MTOP PA 8" + HANA/UTAC
FDMA1024NZ	PT4 N Z	MLP	FCS MTOP PA 8" + No Change
FDD8453LZ	PT4 N Z	DPAK_JEDEC_SZ	FCS MTOP PA 8" + No Change
FDMA1028NZ_F106	PT4 N Z	MLP	FCS MTOP PA 8" + No Change
PCF430NZW	PT4 N Z	XSWFR_CB	FCS MTOP PA 8" + No Change
FDMA1024NZ_F130	PT4 N Z	MLP	FCS MTOP PA 8" + No Change
FDMA1028NZ	PT4 N Z	MLP	FCS MTOP PA 8" + No Change
FDMA1028NZ_F021	PT4 N Z	MLP	FCS MTOP PA 8" + No Change
FDMA2002NZ_F130	PT4 N Z	MLP	FCS MTOP PA 8" + No Change
FDS8813NZ	PT4 N Z	SO8	FCS MTOP PA 8" + No Change
FDS8817NZ	PT4 N Z	SO8	FCS MTOP PA 8" + No Change
FDS8817NZ_G	PT4 N Z	SO8	FCS MTOP PA 8" + No Change
FDS8817NZ_S8SP001	PT4 N Z	SO8	FCS MTOP PA 8" + No Change
FR015L3EZ	PT4 N Z	MLP	FCS MTOP PA 8" + HANA
FDME1026NZT	PT4 N Z	MLP	FCS MTOP PA 8" + HANA

Reason for Change:
 Improve supply flexibility.
 Better quality and yields through equipment and facility upgrades.
 - Increased automation in handling and inspection in assembly.

Fairchild partners with foundries and assembly subcontractors.

- Best manufacturing practices, access to many customers methods and practices.
- Advanced technology for fast ramp of future new products and technologies.

Affected Product(s): Please refer to the list of affected products in the addendum attached in the PCN email you received. This list is based on an analysis of your company's procurement history.

Qualification Plan	Device	Package	Process	No. of Lots
Q20140414	FDD8453LZ_F085	D-PAK	PT4NZ	3

Test Description:	Condition:	Standard:	Duration:	Results:
Precon	MSL1, 260C	JESD22A-113	NA	10-May
Temperature Cycle	-55C, 150C	JESD22-A104	1000 cyc	6-June
High Temperature Storage Life	175C	JESD22-A103	1000 hrs	30-June
Power Cycle	Delta 100C, 2 Min On/Off	JESD22-A122	15000 cyc	30-June
Highly Accelerated Stress Test	130C, 85%RH, 32V	JESD22-A110	96 hrs	20-May
Un-bias HAST	130C, 85%RH,	JESD22-A118	96 hrs	20-May
High Temperature Gate Bias	175C, 20V	JESD22-A108	1000 hrs	25-June
High Temperature Reverse Bias	175C, 40V	JESD22-A108	1000 hrs	25-June
RSDH	270C	JESD22-B106	15 sec	17-May

Qualification Plan	Device	Package	Process	No. of Lots
Q20140414	FDZ372NZ	WLCSP	PT4 NZ	3

Test Description:	Condition:	Standard:	Duration:	Results:
Highly Accelerated Stress Test	85%RH, 130C, +16V	JESD22-A110	96 hrs	27-May
High Temperature Reverse Bias	125C, +16V	JESD22-A108	1000 hrs	14-July
High Temperature Gate Bias	150C, +8V	JESD22-A108	1000 hrs	14-July
Temperature Cycle	-55C, 150C	JESD22-A104	1000 cyc	2-July
Power Cycle	Delta125CC,2 Min cycle	MILSTD-750-1036	10000 cyc	25-June

Qualification Plan	Device	Package	Process	No. of Lots
Q20140219	FDS4675	SOIC 8L	PT2 P	1

Test Description:	Condition:	Standard:	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	JESD22-A113	NA	0/308
MSL1	260C, 3 cycles	J-STD_020	NA	0/22
Highly Accelerated Stress Test	130C, 85%RH, -32V	JESD22-A110	96 hrs	0/77
High Temperature Storage Life Test	150C	JESD22-A103	500 hrs	0/77
UnBiased Highly Accelerated Stress Test	130C, 85%RH	JESD22-A118	96 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	1000 cyc	0/77
High Temperature Gate Bias	150C, -20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, -40V	JESD22-A108	1000 hrs	0/77
Power Cycle	Delta 100CC, 2 Min cycle	MIL-STD-750-1036	15000 cyc	21-Apr
Lead Fatigue	15Degree, 3X	JESD22-B105		0/30
Resistance to Solder Heat	Solder Dip = 260C	JESD22-B106	10 sec	0/10
Solderability	Condition C steam aging (8hrs), Condition A solder Dip (245 for 5 sec)	JESD22-B102	NA	0/10

Qualification Plan	Device	Package	Process	No. of Lots
Q20140219	SI4467DY	SOIC 8L	PT2 P	2

Test Description:	Condition:	Standard:	Duration:	Results:
MSL3 Precondition	260C, 3 cycles	JESD22-A113	NA	0/616
MSL3	260C, 3 cycles	J-STD_020	NA	0/44
Highly Accelerated Stress Test	130C, 85%RH, -16V	JESD22-A110	96 hrs	0/154
High Temperature Storage Life Test	150C	JESD22-A103	500 hrs	0/154
UnBiased Highly Accelerated Stress Test	130C, 85%RH	JESD22-A118	96 hrs	0/154
Temperature Cycle	-65C, 150C	JESD22-A104	1000 cyc	0/154
High Temperature Gate Bias	150C, -8V	JESD22-A108	1000 hrs	0/154
High Temperature Reverse Bias	150C, -20V	JESD22-A108	1000 hrs	0/154
Power Cycle	Delta 100CC, 2 Min cycle	MIL-STD-750-1036	15000 cyc	0/154
Lead Fatigue	15Degree, 3X	JESD22-B105		0/60
Resistance to Solder Heat	Solder Dip = 260C	JESD22-B106	10 sec	0/20
Solderability	Condition C steam aging (8hrs), Condition A solder Dip (245 for 5 sec)	JESD22-B102	NA	0/20

Qualification Plan	Device	Package	Process	No. of Lots
Q20140111C	FDN304PZ	SSOT3	PT2P Z	3

Test Description:	Condition:	Standard:	Duration:	Results:
High Temperature Gate Bias	150°C, Vgs = - 8V	JESD22-A108	1000 hrs	19-June
High Temperature Reverse Bias	150°C, Vr = - 20V	JESD22-A108	1000 hrs	19-June

Qualification Plan	Device	Package	Process	No. of Lots
Q20140001	FDMC6676BZ	MLP	ST3PZ	3

Test Description:	Condition:	Standard:	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	JESD22-A113	NA	0/540
Highly Accelerated Stress Test	130C, 85%RH, -24V	JESD22-A110	96 hrs	0/231
High Temperature Storage Life Test	150C	JESD22-A103	500 hrs	0/231
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/231
High Temperature Gate Bias	150C, -25V	JESD22-A108	1000 hrs	0/231
High Temperature Reverse Bias	150C, -24V	JESD22-A108	1000 hrs	0/231
Power Cycle	Delta 100CC, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/231

Qualification Plan	Device	Package	Process	No. of Lots
Q20140002	FDS6681Z_G	SO8	ST3PZ	3

Test Description:	Condition:	Standard:	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	JESD22-A113	NA	0/540
Highly Accelerated Stress Test	130C, 85%RH, -24V	JESD22-A110	96 hrs	0/231
High Temperature Storage Life Test	150C	JESD22-A103	500 hrs	0/231
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/231
High Temperature Gate Bias	150C, -25V	JESD22-A108	1000 hrs	0/231
High Temperature Reverse Bias	150C, -24V	JESD22-A108	1000 hrs	0/231
Power Cycle	Delta 100CC, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/231

Qualification Plan	Device	Package	Process	No. of Lots
Q20140208A	FAN2106MPX	MLDEMC25	Maine CBIH30VD Salt Lake PT3 N/PT3 N S	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140208A	FDMF6704	MLDFNYAR	Jazz US JAZZBC05D Salt Lake RP5 N/RP5 N S	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140208A	FDMS2734	MLDAMC08	Mountain Top UFET Trench	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 42V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, 200V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140208A	FDMS7620S	MLDAMCX8	TSMC Taiwan PT7 N/PT7 N S	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 24V	JESD22-A110	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140208A	FIN210ACMLX	MLDFL032	Maine FS35C3LMD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140208A	FXLA108BQX	MLDFX020	Maine 35CTINYBD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 3.6V	JESD22-A110	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Static Operating Life	150C, 3.6V	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140208A	FDML7610S	MLDEZCX8	Salt Lake PT7 N/PT7 N S	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 24V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	125C, 24V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140208A	FDMA7628	MLDEBCC6	Salt Lake PT4 N	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 16V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 8V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, 16V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140208A	FDMC6683	MLDEUC08	Salt Lake ST3 P	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, -16V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, -8V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, -16V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140208A	FDMC86261P	MLDEUC08	Salt Lake MV5 P	1

Test Description:	Condition:	Standard:	Duration:	Results:
High Temperature Reverse Bias	150C, -120V	JESD22-A108	1000 hrs	0/77
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140207	NC7SV08FHX	PFH88006	Maine 35CTNYBD	3

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/231
Highly Accelerated Stress Test	85%RH, 130C, 3.6V	JESD22-A110	96 hrs	0/231
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/231
Static Operating Life	150C, 3.3V	JESD22-A108	1000 hrs	0/231
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/231
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/30
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/33
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/33
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/66

Qualification Plan	Device	Package	Process	No. of Lots
Q20140207	FSA642UMX	PFGOX024	Maine FS35C32BD	3

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/231
Highly Accelerated Stress Test	85%RH, 130C, 4.6V	JESD22-A110	96 hrs	0/231
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/231
Static Operating Life	150C, 4.6V	JESD22-A108	1000 hrs	0/231
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/231
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/30
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/33
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/33
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/66

Qualification Plan	Device	Package	Process	No. of Lots
Q20140207	FDMA6023PZT	MFEJJX06	Bucheon ST3 BGBM	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, -16V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, -8V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, -16V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140207	FPF1018	MFEJJA06	Maine FS35C32BD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 1.8V	JESD22-A110	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Static Operating Life	150C, 1.8V	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140207	FSA9280AUMX	MFFT5020	Maine 35D540SBD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 3.3V	JESD22-A110	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Static Operating Life	150C, Vcc=5.5V, VLD=3.3V	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140207	FSA1211UMX	MFGY5028	Maine FS35C32BD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140207	FXLA0104QFX	PFGGJ012	Maine FS35CD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Unbias Highly Accelerated Stress Test	85%RH, 130C	JESD22-A110	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140207	FSA8038UMSX_F106	PFGDHA10	Maine 35D540BD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 4.5V	JESD22-A110	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Static Operating Life	150C, 3.0V	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140207	NC7SZ00L6X	MLLF4006	Maine C5LBPOAD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 5.0V	JESD22-A110	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Static Operating Life	150C, 5.0V	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140207	FAN256L8X_F106	MLLF5008	Maine FS50BPOAD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 5.0V	JESD22-A110	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Static Operating Life	150C, 5.0V	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140197	NC7SV08FHX	PFH88006	Maine 35CTNYBD	2

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/154
Highly Accelerated Stress Test	85%RH, 130C, 3.6V	JESD22-A110	96 hrs	0/154
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/154
Static Operating Life	150C, 3.3V	JESD22-A108	1000 hrs	0/154
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/154
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/20
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/22
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/22
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/44

Qualification Plan	Device	Package	Process	No. of Lots
Q20140197	FSA642UMX	PFGOX024	Maine FS35C32BD	3

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/231
Highly Accelerated Stress Test	85%RH, 130C, 4.6V	JESD22-A110	96 hrs	0/231
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/231
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/231
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/30
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/33
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/33
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/66

Qualification Plan	Device	Package	Process	No. of Lots
Q20140197	FDMA6023PZT	MFEJJX06	Bucheon ST3 BGBM	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, -16V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, -8V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, -16V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140197	FPF1018	MFEJJA06	Maine FS35C32BD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 1.8V	JESD22-A110	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Static Operating Life	150C, 1.8V	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140197	FSA9280AUMX	MFFT5020	Maine 35D540SBD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 3.3V	JESD22-A110	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Static Operating Life	150C, Vcc=5.5V, VLD=3.3V	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140197	FSA1211UMX	MFGY5028	Maine FS35C32BD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140192	FDMS2734	MLDAMC08	Mountain Top UFET Trench	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 42V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, 200V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140192	FDMS7620S	MLDAMCX8	Salt Lake PT7 N/PT7 N S	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 24V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	125C, 24V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140192	FIN210ACMLX	MLDFL032	Maine FS35C3LMD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Unbias Highly Accelerated Stress Test	85%RH, 130C	JESD22-A110	96 hrs	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140192	FXLA108BQX	MLDFX020	Maine 35CTINYBD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 3.6V	JESD22-A110	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Static Operating Life	150C, 3.6V	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140192	FDML7610S	MLDEZCX8	Salt Lake PT7 N/PT7 N S	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 24V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	125C, 24V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140192	FDMC86261P	MLDEUC08	Salt Lake MV5 P	1

Test Description:	Condition:	Standard:	Duration:	Results:
High Temperature Reverse Bias	150C, -120V	JESD22-A108	1000 hrs	0/77
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20150051	FAN2106MPX	MLDEMC25	Maine CBIH30VD Salt Lake PT3 N/PT3 N S	1

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20150051	FDMF6704	MLDFNYAR	Jazz US JAZZBC05D Salt Lake RP5 N/RP5 N S	2

Test Description:	Condition:	Standard:	Duration:	Results:
Autoclave	100%RH, 121C	JESD22-A102	96 hrs	0/154
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/154
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/154
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/20
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/22
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/22
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/44

Qualification Plan	Device	Package	Process	No. of Lots
Q20140194	FDS6910	NMSOD 8L	Salt Lake PT3 N	1

Test Description:	Condition:	Standard:	Duration:	Results:
Highly Accelerated Stress Test	85%RH, 130C, 24V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, 24V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Lead Integrity	30 degree, 3Oz.	JESD22-B105	3 cyc	0/10
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140194	FDS2734	NMSON 8L	Mountain Top UFET TRENCH	1

Test Description:	Condition:	Standard:	Duration:	Results:
High Temperature Reverse Bias	150C, 200V	JESD22-A108	1000 hrs	0/77
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140194	FDS6699S	NMSON 8L	Salt Lake PT3 N S	1

Test Description:	Condition:	Standard:	Duration:	Results:
Highly Accelerated Stress Test	85%RH, 130C, 24V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	125C, 24V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Lead Integrity	30 degree, 3Oz.	JESD22-B105	3 cyc	0/10
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140194	FDS6982AS	NMSOD 8L	Mountain Top/Salt Lake PT3 N/PT3 N S	1

Test Description:	Condition:	Standard:	Duration:	Results:
Highly Accelerated Stress Test	85%RH, 130C, 24V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	125C, 24V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Lead Integrity	30 degree, 3Oz.	JESD22-B105	3 cyc	0/10
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140194	FDS8858CZ	NMSOD 8L	Salt Lake PT4 N Z/ST3 P Z	1

Test Description:	Condition:	Standard:	Duration:	Results:
Highly Accelerated Stress Test	85%RH, 130C, Q1:24/Q2:-24V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, Q1:20/Q2:-25V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, Q1:24/Q2:-24V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Lead Integrity	30 degree, 3Oz.	JESD22-B105	3 cyc	0/10
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22